



Sponsorship Opportunities

The 3D InCites Awards program was established in 2013 in conjunction with TechSearch International to recognize achievements that further the commercialization of 2.5D and 3D IC technologies. The 2014 Awards Program will be launched at the European 3D TSV Summit with the announcement of this year's sponsors, details for participation and a call for nominations. The awards will be presented during a breakfast ceremony at SEMICON West 2014.

Sponsorship opportunities for the 2014 3D InCites Awards Program are now available for companies who wish to promote their business for the duration of the 2014 program. Proceeds of the 2014 program will benefit the Frances B. Huggle Engineering Scholarship, as well as fund other STEM-based educational programs.

Platinum Sponsor: \$5000 (Limit 2)

- On-stage participation in Awards Ceremony and photo opportunity with winners
- Top-level branding, including preferred logo placement/branding on:
 - Signage at the Awards Ceremony
 - 3D InCites Award Program page
 - 3DInCites homepage under awards logo
 - "Countdown to 3D InCites Awards" eNL updates
 - 3D InCites Award Winners showcase
 - Banner advertisement for the Award and/or event (tentative)
 - Acknowledgement in all Award Program materials
 - Listing as Platinum Sponsor in program presentation

Silver Sponsors: \$2000

- Logo placement/branding on:
 - 3DInCites homepage under Platinum Sponsors and logo
 - 3DInCites Award program page
 - 3D InCites Award Winners showcase
 - "Countdown to 3D InCites Awards" eNL updates
 - Signage at the Awards Ceremony
 - Listing as Silver Sponsor in program presentation

